

What is Claimed is.

1. An apparatus for polishing a substrate, comprising:

a roll;

a polishing pad, to be wound by said roll, for polishing a substrate;

5 a motor connected to said roll for taking up said polishing pad;

a sensor for detecting wear of said polishing pad; and

a controller for energizing said motor according to a signal from said sensor.

2. The apparatus according to claim 1, further comprising a brush for

10 removing ground-off material produced during a polishing process.

3. The apparatus according to claim 1, further comprising an atomizer for spraying a gas-liquid mixture onto said polishing pad.

15 4. The apparatus according to claim 1, further comprising an optical sensor for monitoring thickness of a film of the substrate.

5. The apparatus according to claim 1, wherein said polishing pad is mounted on a first polishing table, and a polishing pad is mounted on a second 20 polishing table.

6. The apparatus according to claim 5, wherein said polishing pad mounted on said first polishing table comprises a fixed abrasive pad.

25 7. The apparatus according to claim 5, wherein said polishing pad mounted on said second polishing table comprises a polyurethane foam pad.

8. An apparatus for polishing a substrate, comprising:
a roll;
a polishing pad, to be wound by said roll, for polishing a substrate;
a motor connected said roll for taking up said polishing pad;

5 a sensor for detecting a condition of said polishing; and
a controller for energizing said motor according to a signal from said sensor.

9. An apparatus for polishing a substrate, comprising:
a roll;
10 a polishing pad, to be wound by said roll, for polishing a substrate;
a plurality of polishing tables, said polishing pad be mounted on at least one
of said polishing tables;
a motor connected to said roll for taking up said polishing pad;
a sensor for detecting a condition of said polishing pad; and
15 a controller for energizing said motor according to a signal from said sensor.

10. The apparatus according to claim 9, wherein polishing pad comprises
a fixed abrasive pad.

20 11. A method of treating a substrate, comprising:
polishing a substrate by pressing said substrate against a polishing pad which
is wound on a roll;
detecting wear of said polishing pad by a sensor;
sending a signal to a controller; and
25 taking up said polishing pad after said controller receives said signal.

12. The method according to claim 11, wherein sending of said signal is performed when said sensor detects said wear of said polishing pad.

13. The method according to claim 11, wherein said taking up of said
5 polishing pad is performed by a motor energized by said controller.

14. The method according to claim 11, further comprising:
applying ultra violet radiation for deteriorating said polishing pad.

10 15. The method according to claim 11, further comprising:
applying electromagnetic waves for measuring thickness a film of said
substrate.